

Vishay General Semiconductor

Surface Mount Glass Passivated Rectifier

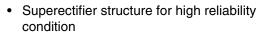


* Glass-plastic encapsulation technique is covered by patent No. 3,996,602, brazed-lead assembly by Patent No. 3,930,306 and lead forming by Patent No. 5,151,846

DO-214BA (GF1)

MAJOR RATINGS AND CHARACTERISTICS							
I _{F(AV)}	1.0 A						
V_{RRM}	50 V to 1000 V						
I _{FSM}	30 A						
V _F	1.1 V, 1.2 V						
I _R	5.0 μΑ						
T _j max.	175 °C						

FEATURES





- Patented glass-plastic encapsulation technique
- · Ideal for automated placement
- · Low forward voltage drop
- · Low leakage current
- · High forward surge capability
- · Meets environmental standard MIL-S-19500
- Meets MSL level 1, per J-STD-020C, LF max peak of 250 °C
- Solder Dip 260 °C, 40 seconds
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

TYPICAL APPLICATIONS

For use in general purpose rectification power supplies, inverters, converters and freewheeling diodes for consumer, automotive and telecommunication.

MECHANICAL DATA

Case: DO-214BA, molded epoxy over glass body

Epoxy meets UL 94V-0 flammability rating

Terminals: Matte tin plated leads, solderable per

J-STD-002B and JESD22-B102D

E3 suffix for commercial grade, HE3 suffix for high

reliability grade (AEC Q101 qualified)

Polarity: Color band denotes cathode end

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)									
PARAMETER	SYMBOL	GF1A	GF1B	GF1D	GF1G	GF1J	GF1K	GF1M	UNIT
Device marking code		GA	GB	GD	GG	GJ	GK	GM	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T _L = 125 °C	I _{F(AV)}	1.0						Α	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	30						Α	
Operating junction and storage temperature range	T _J , T _{STG}	- 65 to + 175						°C	

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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)										
PARAMETER	TEST CONDITIONS	SYMBOL	GF1A GF1B GF1D GF1G GF1J GF1K G				GF1M	UNIT		
Maximum instantaneous forward voltage	at 1.0 A	V _F	1.1				1.1 1.2		.2	V
Maximum DC reverse current at rated DC blocking voltage	T _A = 25 °C T _A = 125 °C	I _R	5.0 50					μΑ		
Typical reverse recovery time	at $I_F = 0.5 \text{ A}$, $I_R = 1.0 \text{ A}$, $I_{rr} = 0.25 \text{ A}$	t _{rr}	3.0			μs				
Typical junction capacitance	at 4.0 V, 1 MHz	CJ	15					pF		

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)								
PARAMETER SYMBOL GF1A GF1B GF1D GF1G GF1J GF1K GF1M UN							UNIT	
Typical thermal resistance ⁽¹⁾	$R_{ hetaJA} \ R_{ hetaJL}$	80 26				°C/W		

Note:

(1) Thermal resistance from junction to ambient and from junction to lead, P.C.B. mounted on 0.2 x 0.2" (5.0 x 5.0 mm) copper pad areas

ORDERING INFORMATION								
PREFERRED P/N	UNIT WEIGHT (g)	REFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE				
GF1J-E3/67A	0.104	67A	1500	7" Diameter Plastic Tape & Reel				
GF1J-E3/5CA	0.104	5CA	6500	13" Diameter Plastic Tape & Reel				

RATINGS AND CHARACTERISTICS CURVES

(T_A = 25 °C unless otherwise noted)

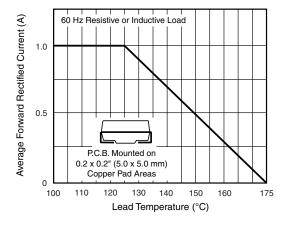


Figure 1. Forward Current Derating Curve

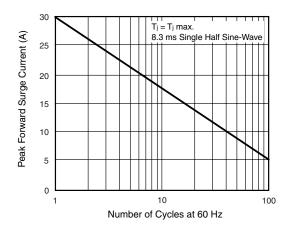


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current



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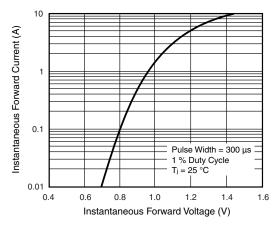


Figure 3. Typical Instantaneous Forward Characteristics

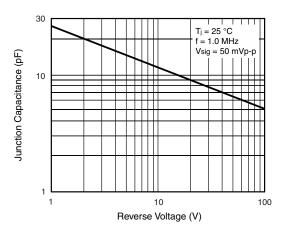


Figure 5. Typical Junction Capacitance

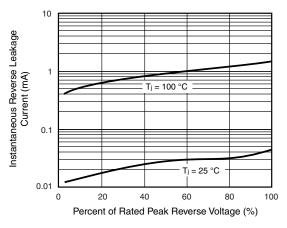


Figure 4. Typical Reverse Characteristics

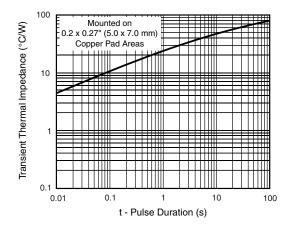


Figure 6. Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

DO-214BA (GF1) Cathode Band **Mounting Pad Layout** 0.066 (1.68) 0.076 MAX. 0.066 MIN. (1.93 MAX.) 0.040 (1.02) (1.68 MIN.) 0.187 (4.75) 0.167 (4.24) 0.015 (0.38) 0.060 MIN. 0.0065 (0.17) (1.52 MIN.) 0.118 (3.00) 0.108 (2.74) 0.098 (2.49) 0.100 (2.54) 0.220 (5.58) REF 0.114 (2.90) 0.006 (0.152) TYP 0.060 (1.52) 0.094 (2.39) 0.030 (0.76) 0.226 (5.74) 0.196 (4.98)

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